



INFORMATION DISCLOSURE STATEMENT

Applicant : Camm, et al.
 App. No. : 10/005,186
 Filed : December 4, 2001
 For : HEAT-TREATING METHODS AND SYSTEMS
 Examiner : S Fuqua
 Group Art Unit : 3742

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TECHNOLOGY CENTER R3700

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Dear Sir:

Enclosed is form PTO-1449 listing 16 references that are also enclosed.

This Information Disclosure Statement is being filed before the receipt of a first Office Action on the merits, and presumably no fee is required in accordance with 37 C.F.R. § 1.97(b)(3). If a first Office Action on the merits was mailed before the mailing date of this Statement, the Commissioner is authorized to charge the fee set forth in 37 C.F.R. § 1.17(p) to Deposit Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated:

March 8, 2004

By:

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INFORMATION DISCLOSURE CITATION
 (Use several sheets if necessary)

 Atty. Docket No.
FETHE24.001 CP1 (47753-Scip)

Serial No. 10/005,186

 Applicant(s)
David M. Camm, et al.

 Filing Date
December 4, 2001

Group

U.S. PATENT DOCUMENTS
OTHER ART (including Author, Title, Date, Pertinent Pages, Etc.)

AI	Lord, H.A., "Thermal and Stress Analysis of Semiconductor Wafers in a Rapid Thermal Processing Oven", (August 1988), Vol. 1, No. 3, IEEE Transactions on Semiconductor Manufacturing, p. 105-114.
AJ	Hill, C., et al., "Rapid Thermal Annealing - Theory and Practice", in <i>Reduced Thermal Processing for VLSI</i> , (New York: Plenum, 1989), p. 143-180.
AK	Kakoschke, R., "Is There a Way to a Perfect Rapid Thermal Processing System?", (1991), Vol. 224, Mat. Res. Soc. Symp. Proc., p. 159-170.
AL	Kakoschke, R., et al., "Simulation of Temperature Effects During Rapid Thermal Processing", (1989), Vol. 146, Mat. Res. Soc. Symp. Proc., p. 473-482.
AM	Vandenabeele, P., et al., "Impact of Patterned Layers on Temperature Non-Uniformity During Rapid Thermal Processing for VLSI-Applications", (1989), Vol. 146, Mat. Res. Soc. Symp. Proc., p. 149-160.
AN	Nulman, J., et al., "Pyrometric Emissivity Measurements and Compensation in an RTP Chamber", (1989), Vol. 146, Mat. Res. Soc. Symp. Proc., p. 461-466.
AO	Dilhac, J-M., et al., "Adaptive Process Control for a Rapid Thermal Processor", (1990), SPIE Vol. 1393, Rapid Thermal and Related Processing Techniques, p. 395-403.
AP	Dilhac, J-M., et al., "Thermal Model for Rapid Thermal Processors: Theory and Applications", (1993), RTP '93 conference proceedings, p. 12-18.
EXAMINER	
DATE CONSIDERED	

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